

Silicon N Channel Power MOSFET

Description

The HXN0360 is n-channel power MOSFET are produced using high cell density , Trench MOSFET technology.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, power management.

Features

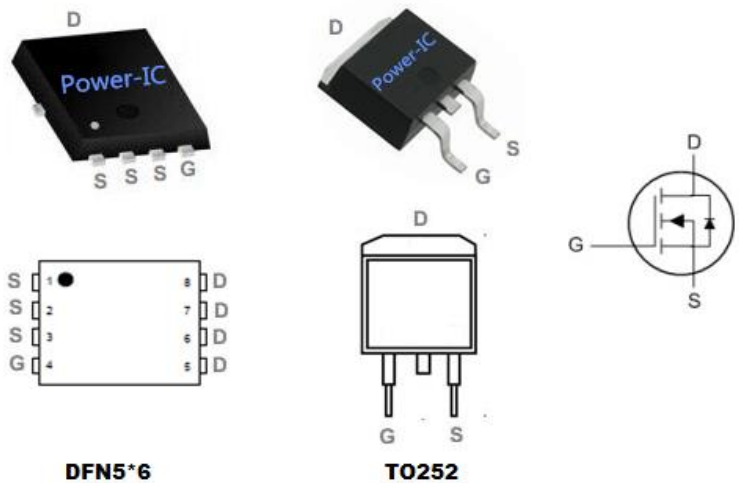
- Latest Trench Power MOSFET technology
- Low On-state Resistance
- High Current Density
- Low Gate Charge
- 100% UIS Test

Product Summary

- BVDS \geq 30V
- RDS(ON) \leq 9m Ω @VGS=10V
- RDS(ON) \leq 11.5m Ω @VGS=4.5V

Applications

- Motor Driver
- Power Management



Silicon N Channel Power MOSFET**1、 Absolute maximum ratings**

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	30	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $TC = 25\text{ }^\circ\text{C}$	60	A
$I_{DM}^{(2)}$	Drain current (pulsed)	240	A
P_D	Power dissipation at $TC = 25\text{ }^\circ\text{C}$	80	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	200	mJ
T_j	Operating junction temperature	-55 to 150	$^\circ\text{C}$

1. Current limited by package
2. Pulse width limited by safe operating area
3. Starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = 20\text{A}$, $V_{DD} = 30\text{V}$, $L = 1\text{mH}$

2、 Thermal data

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		85		$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case		70		$^\circ\text{C}/\text{W}$

3、 Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$	30			V
I_{DSS}	Zero gate voltage drain	$V_{DS} = \text{Max rating}$			1	μA
I_{GSS}	Gate body leakage current	$V_{GS} = \pm 20\text{V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$	1	1.6	2	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{V}$, $I_D = 30\text{A}$			9	m Ω
		$V_{GS} = 4.5\text{V}$, $I_D = 30\text{A}$			11.5	m Ω

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C_{iss}	Input capacitance	$V_{DS} = 15V$		1600		pF
C_{oss}	Output capacitance	$f = 1 \text{ MHz}$		180		pF
C_{rss}	Reverse transfer	$V_{GS} = 0$		90		pF
Q_g	Total gate charge	$V_{DD} = 15V$		20		nC
Q_{gs}	Gate-source charge	$I_D = 10A$		9		nC
Q_{gd}	Gate-drain charge	$V_{GS} = 4.5V$		7		nC
I_{SD}	Source-drain current				60	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				240	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 60A, V_{GS} = 0$			1.2	V

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μ s, duty cycle 1.5%